REMARKS

Claims 1-8, 12 and 17-20 were rejected under 35 U.S.C. §102(b) as being anticipated by Nishihara et al. (US 5,118,458). Claims 9-10, 13 and 14 were rejected under 35 U.S.C. §103(a) as being unpatentable over Nishihara et al. (US 5,118,458) in view of Official Notice. Claims 11 and 15 were rejected under 35 U.S.C. §103(a) as being unpatentable over Nishihara et al. (US 5,118,458) in view of Official Notice and Politycki et al. (US 3,767,538). Claim 16 was rejected under 35 U.S.C. §103(a) as being unpatentable over Nishihara et al. (US 5,118,458) in view of Official Notice, Politycki et al. (US 3,767,538) and Murakami et al. (US 4,239,813). The examiner is requested to reconsider these rejections.

Claim 1, as amended, relates to a process of manufacturing. The process comprises forming a cover member for an electronic device, incorporating electrical circuitry into the cover during the formation, and providing on the cover an integral connector structure for connecting the electrical circuitry to an electronic component.

The cover for the electronic device formed by the claimed invention provides the advantage that it reduces the amount of space required within the electronic device for electronic circuitry. Other electronic components can be connected to the circuitry within the cover by means of the integral connecting structures.

Nishihara discloses a method for moulding an article integrated with a multi-layer flexible circuit. The method involves forming a flexible circuit by using a thermosetting

conductive paste to trace a circuit pattern on the surface of a film substrate. The film substrate has an adhesive layer. The flexible circuit is then placed in a mould and moulding material is injected into the mould. The process can be repeated several times to allow several layers of flexible circuits to be built up one on top of the other. Nishihara also discloses connecting electrical parts such as capacitors or transistors to the multi-layer flexible circuit.

Nishihara does not relate to a method of moulding a cover for an electronic device. Nishihara only discloses manufacturing an article such as a printed circuit board having components within it. It does not relate to manufacturing a cover for an electronic device. Nishihara does not disclose anything relating to the density of component packaging in electronic devices.

Furthermore Nishihara also does not disclose providing integral connecting structure for connecting electrical circuitry to an electronic component on the cover. Although Nishihara discloses connecting electrical parts such as capacitors or transistors to the multi-layer flexible circuit, it does not disclose using integral connecting structures to connect these.

The features of claim 1 are not "anticipated" by Nishihara. Nor are the features of claim 1 suggested by Nishihara; either alone or in combination with the other art of record. Therefore, claim 1 is patentable and should be allowed.

Though dependent claims 2-20 contain their own allowable subject matter, these claims should at least be allowable due

to their dependence from allowable claim 1. However, to expedite prosecution at this time, no further comment will be made.

Murikami discloses a method for forming printed wiring by electroless deposition. Politycki discloses a method of coating plastic films with metal. Neither Murikami nor Politycki disclose a method of forming a cover of an electronic device having an integrated circuit.

Claim 33 has been added above to claim the features recited therein.

For all of the foregoing reasons, it is respectfully submitted that all of the claims now present in the application are clearly novel and patentable over the prior art of record. Accordingly, favorable reconsideration and allowance is respectfully requested. Should any unresolved issue remain, the examiner is invited to call applicants' attorney at the telephone number indicated below.

Respectfully submitted,

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